

App. No. 10/057525
Office Action Dated June 28, 2004
Amd. Dated November 29, 2004

REMARKS

Reconsideration is respectfully requested in view of the above amendments and following remarks. Claims 1, 5 and 7 have been amended editorially. Support for amendments to claim 1 is at page 6, lines 15-16 and page 8, lines 1-3. No new matter has been added. Claims 1-15 are pending.

Claim 5 is objected to under 37 CFR 1.75(c) as being of improper dependent form. Applicants respectfully traverse the objection as claim 5 has been amended. Withdrawal of the objection is respectfully requested.

Claim rejections - 35 U.S.C. § 112

Claims 5 and 7 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite. Applicants respectfully traverse the rejection. Claims 5 and 7 have been amended. Withdrawal and reconsideration of the rejection is respectfully requested.

Claim rejections - 35 U.S.C. § 103

Claims 1-7, 14 and 15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tschan et al. (US 4,778,845) in view of Kunert (US 4,910,071) and/or Swanson et al. (US 6,054,001). Claims 8-13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tschan et al. in view of Kunert and/or Swanson et al. as applied to claim 1, and further in view of Landrock (Adhesives Technology Handbook). Claims 8, 10 and 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tschan et al. in view of Kunert and/or Swanson et al. as applied to claim 1, and further in view of Hill et al. (US 5,948,194) and/or Duck et al. (US 5,064,494). Applicants respectfully traverse the rejections.

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Claim 1 is directed to a method of securing a panel with an adhesive bonding material, using a hand-held operator manipulatable dispensing device to dispense adhesive bonding material via a nozzle of the device. The device includes a heater arrangement for heating the adhesive bonding material in the dispensing device. The bonding material is subjected to a 2-stage temperature regime. The first stage is a period of heating the bonding material in the dispensing device at a predetermined level prior to dispensing from the nozzle of the device, wherein little to no curing of the adhesive bonding material occurs during the heating in the dispensing device stage. The second stage is a subsequent period of curing in-situ in contact with the glazing panel at a temperature significantly below the heating temperature level in the first stage. Thus, substantially the entire curing of the material occurs in stage two.

Tschan teaches a one-component adhesive and/or sealing mass. The inventive masses are transported through a heatable hose, wherein partial cross-linkage (curing) takes place. Thus, Tschan teaches significant curing occurs in the heatable hose when the material is in the hot state. Therefore, Tschan teaches away from claim 1. Tschan fails to teach or suggest a period of heating the bonding material in the dispensing device at a predetermined level prior to dispensing from the nozzle of the device, wherein little to no curing of the adhesive bonding material occurs during the heating in the dispensing device stage. Furthermore, neither Kunert, Swanson, Landrock, Hill nor Duck, alone or in combination, remedies the deficiencies of Tschan. Withdrawal of the rejection is respectfully requested.

Claims 2-15 depend either directly or indirectly from claim 1. For the reasons discussed above for claim 1, withdrawal of the rejection is respectfully requested.

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In view of the above, favorable reconsideration in the form of a notice of allowance is requested. Any questions or concerns regarding this communication can be directed to the undersigned attorney, John J. Gresens, Reg. No. 33,112, at (612)371.5265.

Respectfully submitted,

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Dated: November 29, 2004

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JJG:mmm